

1 2 3 4 5 6 7 8 9

A

B

C

D

E

F

A

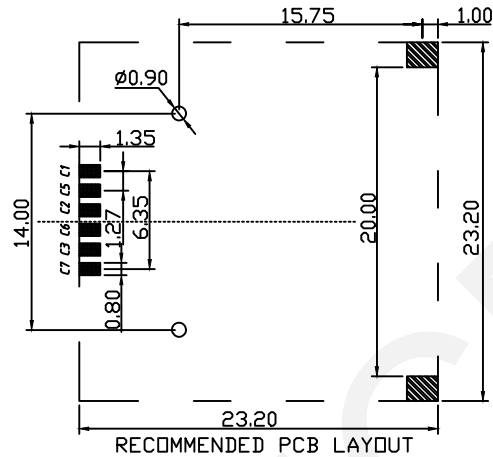
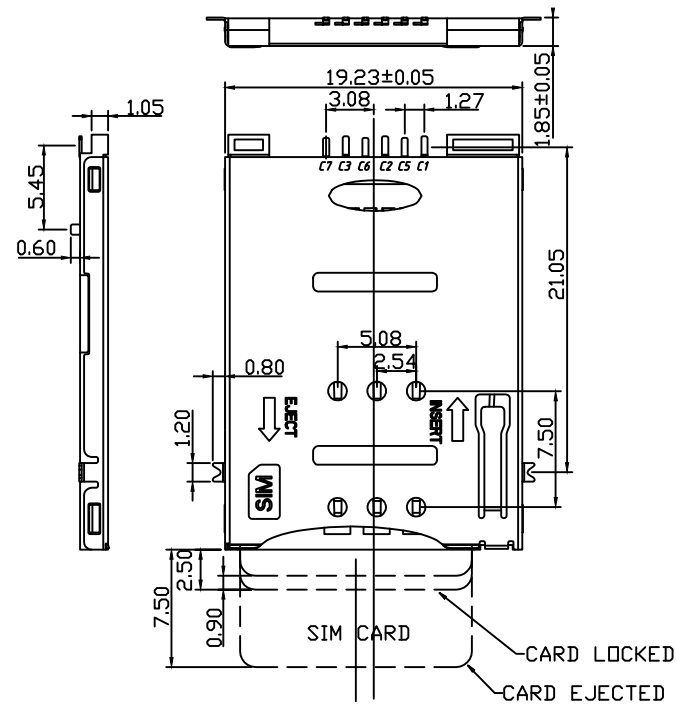
B

C

D

E

F



Material:

Insulator: H-Temperature Plastic, UL 94 V-0, Black.

Contact: Copper Alloy, T=0.15mm

Shell: Stainless Steel, T=0.15mm

Finish:

Terminal: 50u" min Nickel Underplated on Allover, Gold Plating on Contact Area, 80u" min Tin on Solder Tail.

Shell: 50u" Nickel Underplated on Allover, Gold Flash on Solder Latch.

Electrical:

Current Rating: 0.5A, Voltage Rating: 5.0 Vrms.

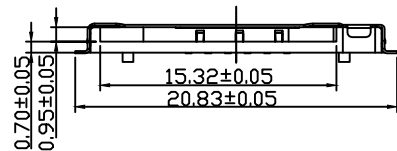
Insulation Resistance: 500M Min. At DC 500V DC

Withstanding Voltage: 250V ACrms For 1 Minute.

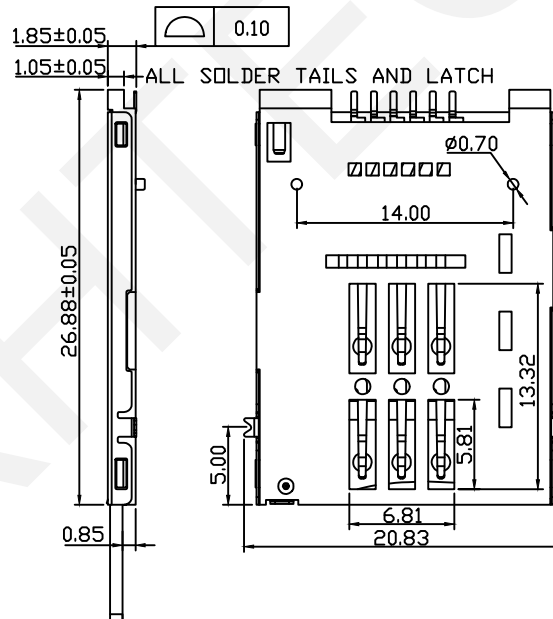
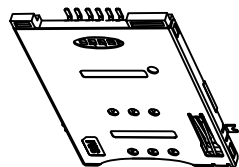
Contact Resistance: 100M Max. At 10mA/20mV MAX.

Operating Temperature: -55°C To +85°C; Mating

Cycles: 5000 Insertions.



SIM PIN Assignment	
Pin#	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved



 NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm

SHEET SIZE: A4

SCALE:---

DRWN BY PAN

SIM CARD CONN; PUSH PUSH, 6P, H1.85, SMD without CD Pin, with Post

0~3

3~18

18~50

50~120

CHK'D BY FENG

±0.12

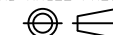
±0.15

±0.3

±0.5

APPR BY ZHAN

THIRD ANGLE PROJECTION



RHTAYIM-073A-6P-0-R

1

2

3

4

5

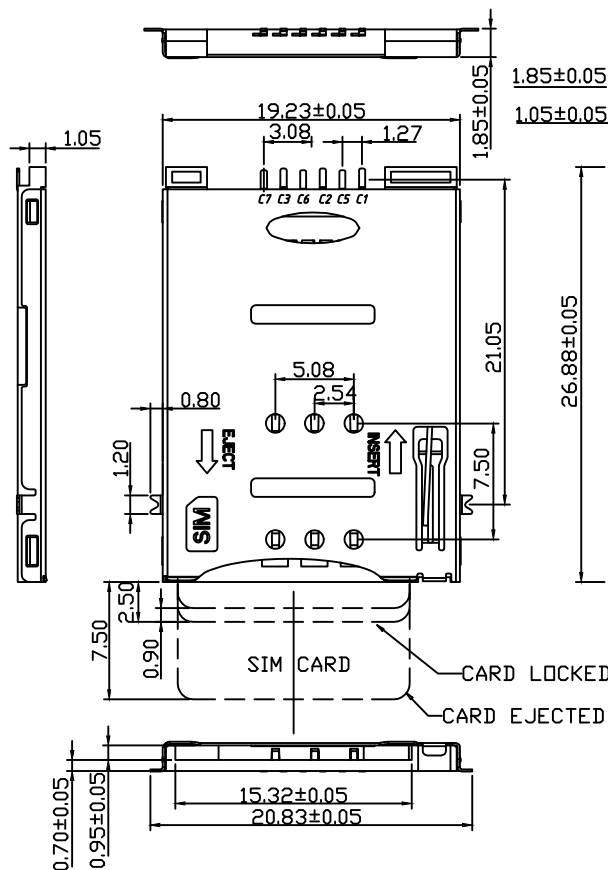
6

7

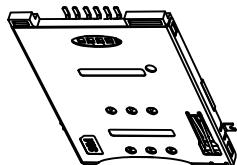
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9

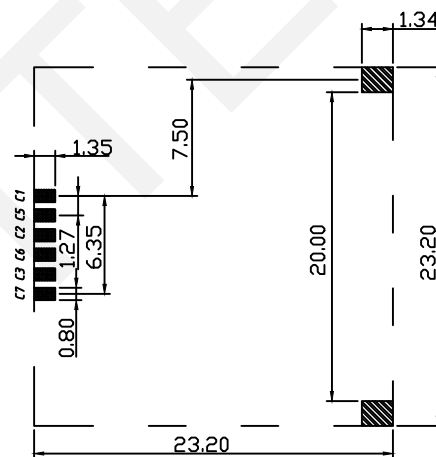
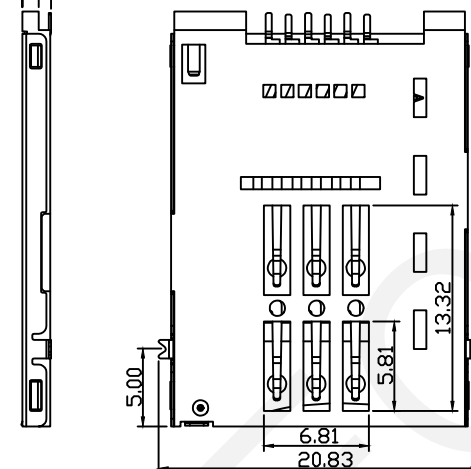
G



Pin#	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved



0.10
ALL SOLDER TAILS AND LATCH



RECOMMENDED PCB LAYOUT

Material:

Insulator: H-Temperature Plastic, UL 94 V-0, Black.

Contact: Copper Alloy, T=0.15mm

Shell: Stainless Steel, T=0.15mm

Finish:

Terminal: 50u" min Nickel Underplated on Allover, Gold Plating on Contact Area, 80u" min Tin on Solder Tail.

Shell: 50u" Nickel Underplated on Allover, Gold Flash on Solder Latch.

Electrical:

Current Rating: 0.5A, Voltage Rating: 5.0 Vrms.

Insulation Resistance: 500M Min. At DC 500V DC

Withstanding Voltage: 250V ACrms For 1 Minute.

Contact Resistance: 100M Max. At 10mA/20mV MAX.

Operating Temperature: -55°C To +85°C; Mating

Cycles: 5000 Insertions.